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RECORDATION FORM COVER SHEET U.S. DEPARTMENT OF COMMERCE FORM PTO-1595 PATENTS ONLY Patent and Trademark Office To the Honorable Commissioner of Patents and Trademarks: Please Record the attached original documents or copy thereof. 2. Name and address of receiving party(ies): Name of conveying party(ies): Name: Sony Corporation SEIJI KUMAGAI JUNICHI HONDA Internal Address: YOSHITA IKEDA Additional name(s) of conveying party(ies) attached? Yes Street Address: 7-35, Kitashinagawa 6-chome 3. Nature of conveyance: Shinagawa-ku, Tokyo 141, Japan City:_ State: Zip: ☐ Merger ☑ Assignment □ Change of Name □ Security Agreement Additional Name(s) & Address(es) attached □ Yes 図 No Other Execution Date February 28, 2000 4. Application (number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: _ 2/28/00_ Patent Application No.(s) B: Patent No.(s) Attorney Docket No. P00,0339 U.S. Serial No. 09/486,140 filed February 22, 2000 Additional numbers attached? □ Yes ☒ No 5. Name and address of party to whom 6. Total number of applications and patents involved correspondence concerning document should be Hill & Simpson, P.C. ☑ Enclosed 85th Floor Sears Tower ☑ Authorized to be charged to deposit account any 233 S. Wacker Drive Additional fees Chicago, IL 60606 8. Deposit Account Number: 08-2290 (Attach duplicate copy of this page if paying by deposit account) 05/11/2000 JSMRRAZZ 00000337 09486140 DO NOT USE THIS SPACE 40.00 OP 9. Statement and signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. David R. Metzger April 25, 2000 Name of Person Signing Date Total number of pages 3 Mail documents to be recorded and required cover sheet information to: **Commissioner of Patents and Trademarks Box Assignments** Washington, D.C. 20231

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PATENT REEL: 010771 FRAME: 0907

ASSIGNMENT

WHEREAS. I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in MAGNETIC HEAD for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS. Sony Corporation, a Japanese corporation with offices at 7-35. Kitashinagawa 6-chome, Shinagawa-ku. Tokyo 141-0001 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. It as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property. Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its design, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto:

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense:

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: <u>PCT/JP99/03327</u>. International Filing Date: June 22, 1999.

This assignment executed on the dates indicated below.

Sciji Kumagai	February 28, 2000
Name of first or sole inventor	Execution date of U.S. Patent Application
Miyagi, Japan Residence of first or sole inventor	
Leji Kumagai	telming 28, 2000
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 010771 FRAME: 0908

Junichi Honda	February 2th, will
Name of second inventor	Execution date of U.S. Patent Application
Miyagi, Japan	
Residence of second inventor	
Signature of Second inventor	February 28, 2008
Signature of second inventor	Date of this assignment
Vashita Ikada	February 28 2000
Yoshito Ikeda Name of third inventor	Execution date of U.S. Patent Application
Name of finia inventor	Execution date of 0.3. Patent Application
Tochigi, Japan	
Residence of third inventor	
Epolito Bila	February 28 2010 Date of this assignment
Signature of third inventor	Date of this assignment